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May 13, 2008

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject: Serial No. 10/796,427 03/09/04

MOU-SHIUNG LIN et al.

"WIREBOND PAD FOR SEMICONDUCTOR CHIP
OR WAFER"

Grp. Art Unit: 2822 LEWIS, MONICA

RESPONSE TO FINAL OFFICE ACTION

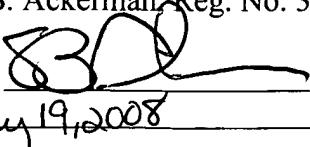
Dear Sir:

In response to the Final Office Action mailed Apr. 16, 2008, please amend the above-identified application for patent and consider the remarks as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on May 19, 2008.

Stephen B. Ackerman, Reg. No. 37,761

Signature 

Date May 19, 2008